IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			ınder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Form Typ Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					erials and M	ials and Mfg Information					
Supplier Inforn	nation																
Company name* Company u				pany unique ID			Unique ID Authority					Respons	Response Date*				
nsemi											2025-07	2025-07-04					
Contact Name		Title - Contact]1	Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stewa	ards	Product Enviro Compliance				NA NA					Produc	Product-Env-Stewards@onsemi.com					
uthorized Represe	Title - Representative			1	Phone - Representative*					Email -	Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com				
Requesto	r Item Number Mfr Item		m Number Mfr Item Name				Effective Da	ate V	e Version M		Manufacturing Site		Weig	ht*	UOM	Unit Type	
		NCP1095DB		Integrated PoE-PD Interface Controller, IEEE 802.3bt, 90W			2025-07-04		BE4			57.52		mg	Each		
Ianufacturing	Proccess Information	on															
Terminal	Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	20 MSL Rating		Peak Process Body Temperatur		ure M	ire Max Time at Peak Tempe		ture	Number	of Reflow Cyc	les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260		С		30 seco		ıds	3			
Comments																	
TTENTION: MSI	3 Rated item requires l	Bake and D	ry Pack (afte	r electrical test)													
or more informati	on regarding material co	mposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.65	mg	Supplier	Silicon (Si)	7440-21-3		4.65	mg
Die Attach	2.99	mg	Supplier	Silver (Ag)	7440-22-4		2.2425	mg
			Supplier	Epoxy resins	129915-35-1		0.7475	mg
Lead Frame	19.55	mg	Supplier	Zinc (Zn)	7440-66-6		0.0195	mg
			Supplier	Iron (Fe)	7439-89-6		0.4496	mg
			Supplier	Copper (Cu)	7440-50-8		19.0612	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0195	mg
Mold Compound-Black	29.75	mg		Epoxy resin	proprietary data		2.2313	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7438	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.2313	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1487	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		24.395	mg
Plating	0.15	mg	Supplier	Palladium (Pd)	7440-05-3		0.0114	mg
			В	Nickel (Ni)	7440-02-0		0.1365	mg
			Supplier	Gold (Au)	7440-57-5		0.0021	mg
Wire Bond - Au	0.43	mg	Supplier	Gold (Au)	7440-57-5		0.43	mg